LB-01
www.oxfordplasma.de/process/si_ns_gc.htm

OXFORD INSTRUMENTS

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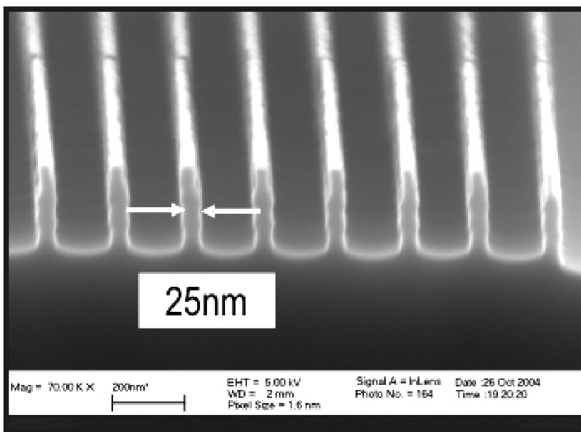
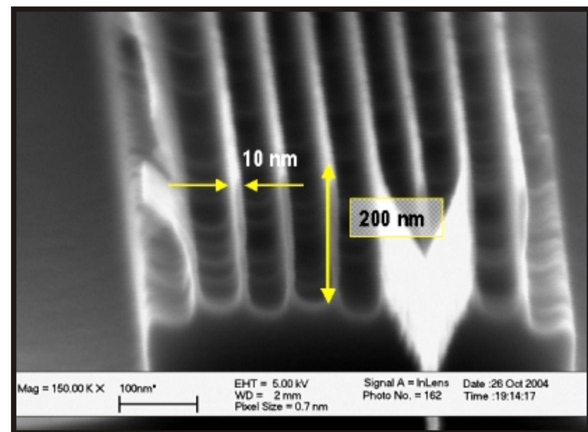
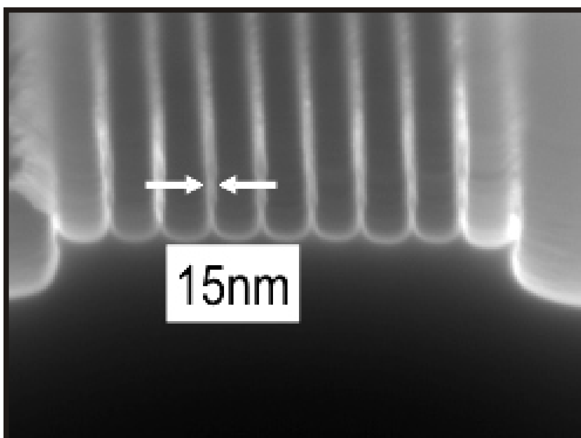
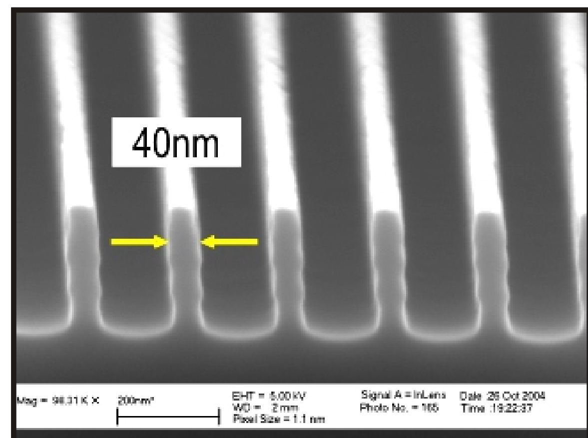
Plasmalab Data

Nanoscale Si Etching by Gas Chopping







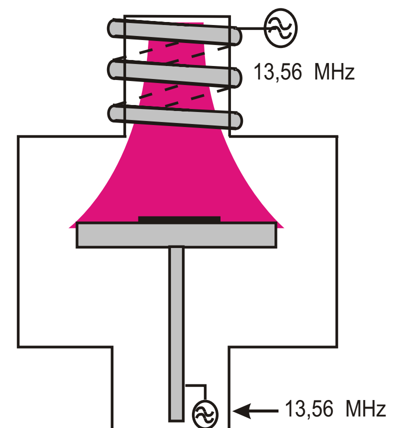


Plasmalab 80 Plus

Plasmalab System 100

Plasmalab System 133

Technology:
Reactive Ion Etching
Inductive Coupled Plasma Source
room temperature process
He backside cooling
process with gas chopping:
isotropic etch/ polymer formation



This results have been obtained at
Lawrence Berkeley National laboratory
by D. L. Olynik and I. W. Rangelow